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PTO/SB/21 (08-00 Please type a plus sign (+) inside this box ™ Approved for use through 10/31/02. OMB 0651-0031 U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number. 10/722.724 **Application Number** TRANSMIT November 25, 2003 Filing Date Peter G. Borden First Inventor 7346 Confirmation No. 2877 **Group Art Unit** (to be used for all correspondence after initial) Rosenberger **Examiner Name** Total Number Of Pages In This Submission **BOX004-1C US** Attorney Docket No. **ENCLOSURES** (check all that apply) Fee Transmittal Form **Assignment Papers** After Allowance Communication to X (1 page in duplicate) (for an Application) Group Appeal Communication to Board of Fee Attached -- Check Drawing(s) Appeals and Interferences Appeal Communication to Group Amendment / Reply Licensing-related Papers (Appeal Notice, Brief, Reply Brief) After Final Petition Proprietary Information Petition to Convert to a Affidavits/declarations Status Letter Provisional Application Power of Attorney, Revocation of Other Enclosure(s) (please identify Previous Powers; And Statement Extension of Time Request Under 37 CFR 3.73(b) Terminal Disclaimer RETURN RECEIPT POSTCARD PTO 1449 (1 page) **Express Abandonment Request** Request for Refund Copies of Fourteen cited references herewith Information Disclosure Statement (2 X CD, Number of CD(s) pages) Certified Copy of Priority Document(s) Remarks This is a Response to Missing Parts/ Please charge Deposit Account 50-2263 for any underpaid fee. Incomplete Application under 37 CFR 1.52 or 1.53 Copy of Notice To File Missing Parts (2 pages) SIGNATURE OF APPLICANT, ATTORNEY OR AGENT

Silicon Valley Patent Group LLP
2350 Mission College Boulevard, Suite 360
Santa Clara, California 95054

Signature

Sept 27, 2004

Omkar K. Suryadevara (Reg. No. 36,320)

EXPRESS MAIL LABEL NO. <u>EV 448 866 784 US</u>.

Modified PTO/SB/17 (09-00)
Approved for use through 10/31/2002. OMB 0651-0032
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		Complete if Known								
FEE TRANSMIT		Application Number	10/722,724							
TPE FOR FY 2004		Filing Date	November 25, 2003							
[S]		First Named Inventor	Peter G. Borden							
EP 2 7 2004 2		Group Art Unit	2877							
REP 2 / ZUVA	n.	Examiner Name	Rosenberger							
TOTAL AMOUNT OF PAYMENT	(\$) 180.00	Attorney Docket No	BOX004-1C US							

METHOD OF PAYMENT	FEE CALCULATION (continued)										
1. The Commissioner is hereby authorized to charge any underpayment and credit any overpayments to:	3. ADD	DITIONAL F	FEES								
Deposit Account Number 50-2263	Large Fee Code	Entity Fee (\$)	Small Fee Code	Entity Fee (\$)	Fee D	escription	Fee Paid				
Deposit Account Silicon Valley Patent Group LLP											
Name Silicon Valley Faterit Group ELP	1051	130	2051	65	Surcha	rge - late filing fee or oath					
Charge Any Additional Fee Required Under 37 CFR 1.16 and 1.17	1052	50	2052	25		irge - late provisional filing cover sheet					
Applicant claims small entity status. See 37 CFR 1.27	1053	130	1053	130	Non-E	nglish specification					
2. 🕱 Payment Enclosed:	1812	2,520	1812	2,520		ng a request for ex parte nination					
	1804	920*	1804	920*		sting publication of SIR prior miner action					
FEE CALCULATION	1805	1,840*	1805	1,840*		sting publication of SIR after ner action					
1. BASIC FILING FEE	1251	110	2251	55	Extens	ion for reply within first montl	n				
	1252	420	2252	210	Extens	ion for reply within second					
Large Entity Small Entity Fee Fee Fee Description Code (\$) Code (\$) Fee	1253	950	2253	475		ion for reply within third					
Paid	1254	1,480	2254	740		ion for reply within fourth					
1001 770 2001 385 Utility filing fee	1255	2,010	2255	1005		ion for reply within fifth montl	n				
1002 340 2002 170 Design filing fee 1003 530 2003 265 Plant filing fee	1401 1402	330 330	2401 2402	165 165		of Appeal a brief in support of an appea	. ———				
1004 770 2004 385 Reissue filing fee	1403	290	2403	145	_	st for oral hearing					
1005 160 2005 80 Provisional filing fee	1451	1,510	1451	1,510		n to institute a public use					
	1452	110	2452	55		n to revive - unavoidable					
SUBTOTAL (1) (\$)0.00	1453	1,300	2453	650	Petitio	n to revive - unintentional					
2. EXTRA CLAIM FEES	1501	1,330	2501	665	Utility	ssue fee (or reissue)	——				
Extra Fee from Fee Paid Claims below	1502	480	2502	240	Design	issue fee					
Total Claims - ** x 18 = \$	1503	640	2503	320	Plant i	ssue fee					
Independent - ** x 86 = \$	1460	130	1460	130		ns to the Commissioner					
Multiple Dependent 0 140 = \$0	1807	50	1807	50	applica						
	1806	180	1806	180	Disclo	ssion of Information sure Statement	180				
Large Entity Small Entity Fee Fee Fee Fee Fee Description Code (\$) Code (\$)	8021	40	8021	40		fing each patent assignment operties (times number of ties)					
1202 18 2202 9 Claims in excess of 20	1809	770	2809	385	rejection	a submission after final on R § 1.129(a))					
1201 86 2201 43 Independent claims in excess of 3	1810	770	2810	385	For ea	ch additional invention to be ned (37 CFR § 1.129(b))					
1203 290 2203 145 Multiple dependent claims, if not paid	1801	770	2801	375	Reque (RCE)	st for Continued Examination					
1204 86 2204 43 "Reissue independent claims over original patent	1802	900	1802	900		st for expedited examination sign application					
1205 18 2205 9 **Reissue claims in excess of 20 and over original patent											
	Other fe	e (specify)									
SUBTOTAL (2) (\$) 0.00 " or number previously paid, if greater; For reissues, see above.	*Reduce	ed by Basic F	iling Fee F	aid		SUBTOTAL (3)	(\$) 180.00				
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SUBMITTED BY	Roo	istration No	,			Complete (if applicable)					
Name (Print/Type) Omkar K. Suryadevara Signature Signature		omey/Agen		36,320	2	Telephone (408) 9	82-8200 ext. 3				
Signature S. (C) Mar						Date Septem	ber 27, 2004				



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Peter G. Borden; Jiping Li;

Assignee: Applied Materials, Inc.

Title: Measuring A Property Of A Layer In A Multilayered Structure

Serial No.: 10/722,724 Filing Date: November 25, 2003

Examiner: Rosenberger Group Art Unit: 2877

Docket No.: BOX004-1C US Confirmation No: 7346

Santa Clara, California September 27, 2004

MAIL STOP AMENDMENT COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §1.97(c)

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, §1.97 and §1.98, the Applicants submit for consideration in the above-identified patent application the document listed on the accompanying Form PTO-1449. Copies of the documents 121-134 are submitted herewith. The remaining documents are not attached hereto, because these documents are issued patents which are readily available in the U.S. Patent and Trademark Office. The Examiner is requested to make these documents of record.

This Information Disclosure Statement is submitted pursuant to 37 CFR §1.97(c) as it is after receipt of a first Office Action on the merits but before mailing of a final Action or Notice of Allowance. Accordingly, a fee is required pursuant to 37 CFR §1.17(p). A Fee Transmittal form (PTO/SB/17) is attached to this submission.

Applicants would appreciate the Examiner initialing and returning the Form PTO-1449, indicating that the information has been considered and made of record herein.

The information contained in this Information Disclosure Statement is to the best of my knowledge and is not to be construed as a representation that: (i) a complete search has been made; (ii) additional information material to the examination of this application does not

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Application No. 10/722,724

exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the above information constitutes prior art to the subject invention.

Via Express Mail Label No. EV 448 866 784 US Respectfully submitted,

Omkar K. Suryadevara Attorney for Applicants Reg. No. 36,320

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U.S. Department of Commerce Patent and Trademark Office	Application No.:
018	Filing Date:
SEP 2 7 2004	First Named Invent
	Group Art Unit:
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Examiner Name:
(Use several sheets if necessary)	Confirmation No.:

		511000 1 01 1
T	Application No.:	10/722,724
	Filing Date:	November 25, 2003
r	First Named Inventor:	Peter G. Borden
ľ	Group Art Unit:	2877
	Examiner Name:	Rosenberger
r	Confirmation No.:	7346
	Attorney Docket No.:	BOX004-1C US

			U.S. P	atent Documents				<u></u>							
*Examiner Intials		Document Number	Subclass		Date if opriate										
	118.	6,211,961	4/3/03	Maris	356	432									
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							Tran	slation							
		Document	Date	Country	Class	Subclass	Yes	No							
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	122.	99/64880	99/64880 16.12.99 WO G01R												
		Other Ar	t (Including Auth	or, Title, Date, Pertinent Pa	ges, Etc.)										
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	125.	J. Opsal, "High Re Materials" Photoa	J. Opsal, "High Resolution Thermal Wave Measurements and Imaging of Defects and Damage in Electronic Materials" Photoacoustic and Photothermal Phenomena II, Springer Series in Optical Sciences, Vol. 62,												
	126.	Rosencwaig, "The	Springer Verlag Berlin, Heidelberg, 1990. Rosencwaig, "Thermal Wave Characterization and Inspection of Semiconductor Materials and Devices", Chapter 5 (pp. 97-135) of Photoacoustic and Thermal Wave Phenomena in Semiconductors, North Holland												
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	130.	International Searc	ch Report PCT/ U	S99/12999											
	131.	International Searc	ch Report PCT/US	603/06239			•								
	132.	International Searc	ch Report PCT/US	501/07475											
	133.	International Searc	ch Report PCT/US	603/06379											
	134.	International Searc	ch Report PCT/US	603/02650											

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^{*} Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.